

SOLDER PASTE

RL-403 No-clean

Contains lead
Medium temperature
Melting point:

183°C





GOOD ADHESION

Paste delicate, Particles small,
Only 20~38 microns



EXCELLENT WETTABILITY

After opening, the surface
remains moist for 36 hours,
Does not affect the welding.

Product display



PRODUCT PARAMETERS

PARAMETER INDEX

ALLOY RATIO	Sn63/Pb37
Viscosity	160~230Pa.s
The size of granule	20-38um
Single capacity	10CC

